



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2022-02-11
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration * Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L9969T-TR	STEH*UR6TCBQ	A	959	2022-02-11
	Amount	UoM	Unit type	ST ECOPACK Grade
	1925	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00838837	

Package Designator	Package Size	Nbr of instances	Shape	
QFP	10.30,7.50,2.28	36	gull wing	
Comment	PowerSSO36			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption id.	Description
7a	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption id.	Description
8(e)	8(e) - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 17th Dec 2021			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.026	die	14
Lead	3.984	soft solder	2070

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GB 26572 – 2014				
Query				Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				true
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
X	O	O	O	O
Soft solder				
Homogeneous Material(s) containing Lead				

QueryList : REACH-17 Jan 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	3.98	Soft solder	2070
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article / Homogeneous Material
Lead	1000 ppm	3.98	Soft solder	975037

QueryList : Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Cobalt, Gold, Tin, Tungsten,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	
Query	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	
Query	Response
The product contains adhesives identified under GB 33372	false

Stockholm Convention Persistent Organic Pollutants	
Query	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	true

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	STEH*UR6TCBQ									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	M-011 Other inorganic materials	10.175	mg	supplier	die	Silicon(Si)	7440-21-3		9.240	mg	908110	4798				
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.005	mg	491	3				
				supplier	metallisation	Copper(Cu)	7440-50-8		0.629	mg	61818	327				
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.001	mg	98	1				
				supplier	metallisation	Gold(Au)	7440-57-5		0.014	mg	1376	7				
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.028	mg	2555	14				
				supplier	metallisation	Palladium(Pd)	7440-05-3		0.022	mg	2162	11				
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	98	1				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.029	mg	2850	15				
				supplier	metallisation	Vanadium(V)	7440-62-2		0.001	mg	98	1				
				supplier	passivation	Silicon oxide	7631-86-9		0.101	mg	9926	52				
				supplier	polymer coating	polyimide	proprietary		0.106	mg	10418	55				
				Leadframe	M-004 Copper and its alloys	159.665	mg	supplier	alloy	Copper(Cu)	7440-50-8		155.390	mg	973225	80722
								supplier	alloy	Iron(Fe)	7439-89-6		3.655	mg	22892	1899
supplier	alloy	Iron phosphide	1310-43-6						0.220	mg	1378	114				
supplier	alloy	Zinc(Zn)	7440-66-6						0.191	mg	1196	99				
supplier	metallization	Silver (Ag)	7440-22-4						0.209	mg	1309	109				
Soft solder	Solder	4.086	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	3.984	mg	975037	2070				
				supplier	solder	Silver(Ag)	7440-22-4		0.061	mg	14929	32				
				supplier	solder	Tin(Sn)	7440-31-5		0.041	mg	10034	21				
Bonding wires	M-004 Copper and its alloys	2.757	mg	supplier	wire	Copper(Cu)	7440-50-8		2.757	mg	1000000	1432				
Encapsulation	M-011 Other inorganic materials	1744.065	mg	supplier	mold compound	Silica vitreous	60676-86-0		1543.498	mg	885000	801817				
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		92.435	mg	53000	48018				
				supplier	mold compound	Phenol resin	205830-20-2		69.763	mg	40000	36241				
				supplier	mold compound	Epoxy type resin	proprietary		34.881	mg	20000	18120				
				supplier	mold compound	Carbon black	1333-86-4		3.488	mg	2000	1812				
Connections coating	Solder	4.252	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.252	mg	1000000	2209				